



## News Release

FOR IMMEDIATE RELEASE

### **Elpida and Winbond Form DRAM Manufacturing Partnership**

**Tokyo, Japan and Taichung, Taiwan, November 11,** – Elpida Memory, Inc. (Tokyo: 6665), Japan’s leading global supplier of Dynamic Random Access Memory (DRAM), and Winbond Electronics Corp. today announced that they have signed a Memorandum of Understanding (MOU) for DRAM foundry services that will see Winbond manufacture DRAMs under contract to Elpida. The outsourcing agreement is the first step of a business partnership the two companies intend to pursue further.

The agreement pertains to the supply of GDDR3 and GDDR5 graphic DRAMs for Elpida. Prior to this agreement Winbond and Elpida have been working together to commercialize GDDR3 and GDDR5 DRAM products. Winbond is preparing to begin commercial production of these products by the end of 2009 while Elpida plans to begin purchasing the output in the first half of 2010.

Under the agreement, Elpida and Winbond will now embark on a more formal business relationship. As a first step Elpida will provide Winbond with advanced DRAM process technology and product technology and in return Winbond will allocate certain capacity at its wafer fabs in Taichung to manufacture these DRAM products. Elpida will purchase the product output and sell it to major customers under its own corporate brand name.

“The partnership we are forming with Winbond is tremendously satisfying,” said Elpida president and CEO Yukio Sakamoto. “The combination of Elpida’s advanced technology and Winbond’s rich product manufacturing experience, which includes graphics memory, will enable us to expand our product lineup across a wide range of applications.”

“Winbond is pleased to form a business partnership with Elpida, world-leading DRAM supplier, starting with a graphic DRAM foundry by using current technology. However, to make this partnership a long and lasting relationship, I believe implementing next generation DRAM process technology from Elpida into our fab will be the best solution for both of us. It will enhance the competitiveness of our specialty DRAM, Mobile RAM as well.” said Arthur Chiao, CEO & Chairman of Winbond Electronics Corporation.

**About Elpida**

Elpida Memory, Inc. (Tokyo: 6665) is a leading manufacturer of Dynamic Random Access Memory (DRAM) integrated circuits. The company's design, manufacturing and sales operations are backed by world class technological expertise. Its 300mm manufacturing facilities, consisting of its Hiroshima Plant and a Taiwan-based joint venture, Rexchip Electronics, utilize the most advanced manufacturing technologies available. Elpida's portfolio features such characteristics as high-density, high-speed, low power and small packaging profiles. The company provides DRAM solutions across a wide range of applications, including high-end servers, mobile phones and digital consumer electronics. More information can be found at <http://www.elpida.com>.

**About Winbond**

Winbond Electronics Corporation (TSE:2344) is the Memory IC company of excellence. The Company provides customer-driven memory solutions backed by the expert capabilities of product design, manufacturing, and sales services.

Winbond owns three main business groups: DRAM Product, NOR Flash and Memory IC Manufacturing. Winbond's product portfolio, consisting of Mobile RAM, Specialty DRAM, Graphics DRAM, and low/medium-density NOR Flash, is widely used by leaders in the consumer, communication, computer peripheral and automobile markets. Based on a 300 mm wafer fab, Winbond keeps pace with the latest technologies to provide high-quality memory IC manufacturing services.

Winbond headquarters in Central Taiwan Science Park, Taiwan, and also has subsidiaries in America, Japan, and Hong Kong. For more information, please visit: <http://www.winbond.com>.

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